

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A polishing composition comprising polymer particles and inorganic particles in an aqueous medium, wherein the inorganic particles have an average particle size of from 5 to 170 ~~95~~ nm, and wherein an average particle size D_p (nm) of said polymer particles and an average particle size D_i (nm) of said inorganic particles satisfy the following formula (1):

$$D_p \leq D_i + 50 \text{ nm} \quad (1)$$

wherein ~~the polymer particles and the inorganic particles are~~
colloidal silica ~~have a zeta potential of zero or the same sign.~~

2. (Original) The polishing composition according to claim 1, wherein the polymer particles are made of a thermoplastic resin.

3. (Original) The polishing composition according to claim 1, wherein the polymer particles are made of a resin having a glass transition temperature of 200°C or less.

4. (Original) The polishing composition according to claim 1, wherein the polymer particles are made of a resin having a degree of cross-linking of 50 or less.

5. (Currently Amended) The polishing composition according to claim 1, wherein the polymer particles and the inorganic particles are colloidal silica have a zeta potential of zero or the same sign.

6. (Original) The polishing composition according to claim 1, wherein a ratio of Cp/Ci is from 0.03 to 2, wherein Cp is a content of the polymer particles in the polishing composition and Ci is a content of the inorganic particles in the polishing composition.

7. (Original) A polishing process for a substrate to be polished comprising polishing the substrate to be polished with the polishing composition as defined in any one of claims 1 to 6.

8. (Currently Amended) A process for improving a rate for polishing a substrate to be polished ~~with~~ using the polishing composition as defined in any one of claims 1 to 6.

9. (Previously Presented) The polishing process according to claim 7, wherein the substrate to be polished is a substrate having silicon dioxide.

*Reply Under 37 CFR § 1.111,
Filed With RCE on March 23, 2005*

*Docket No. 1422-0603P
Appl. No. 10/668,216*

10. (Previously Presented) The polishing process according to claim 7, wherein the substrate to be polished is an aluminum alloy substrate plated with Ni-P.